

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type\*
Distribute

**Declaration Class\*** Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information	G II : ID	III. ID A d. S	D D ( th
1 1	Company Unique ID	1 2	Response Date*
	00-489-5751	D un co Diudonoco	Sat, Jun 15, 2013 02:07 AM
Contact Name *	Title - Contact		Email - Contact *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr It	Mfr Item Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
74VHCT540ASJX	74VHC	T540ASJX	SOP-20 EIA.	ſ			INTE	ERNAL PENANG	0.284052	g	Each	
Manufacturing Process Information												
Terminal Finish	Base Alloy	J-STD-020 MSL Rating			Peak Process Body Temperature		Max Time at Peak Temperature		No Ref	No Reflow cycles		
Matte Tin (Sn)	CU Alloy		1	260 C				30 seconds			3	

<sup>\*</sup> Required Field

## **RoHS Material Composition Declaration**

Declaration Type \* Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \* Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

**Declaration Signature** 

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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## **Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SOP-20 EIAJ

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	1.650	Supplier		Silicon	1.650	7440-21-3	5809
Die Attach	Other Organic Materials	0.812	Supplier		Acrylic Resin	0.175	54208-63-8	615
			Supplier		Silver	0.637	7440-22-4	2244
Encapsulation	Thermoplastics	194.000	В	Antimony/Antimony Compounds	Antimony Trioxide	5.820	1309-64-4	20489
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	1.940	6386-73-8	6830
			Supplier		Carbon Black	1.940	1333-86-4	6830
			Supplier		Epoxy Resin	55.290	29690-82-2	194647
			Supplier		Silica, vitreous	129.010	60676-86-0	454177
Lead Frame	Copper & its alloys	84.200	Supplier		Copper	82.036	7440-50-8	288806
			Supplier		Iron	2.021	7439-89-6	7114
			Supplier		Phosphorus	0.034	7723-14-0	119
			Supplier		Zinc	0.109	7440-66-6	385
Plating	Other Nonferrous metals & alloys	2.850	Supplier		Tin	2.850	7440-31-5	10033
Wire Bond	Precious metals	0.540	Supplier		Gold	0.540	7440-57-5	1901